IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: To Be Assigned Examiner: To Be Assigned

In Re PATENT APPLICATION Of:

Applicants	:	Shigeru YAMADA)
Serial No.	:	To Be Assigned))
Filed	:	October 31, 2003) INFORMATION) DISCLOSURE) STATEMENT
For	:	SEMICONDUCTOR DEVICE HAVING PACKAGING STRUCTURE)
Attorney Ref.	:	OHG 139	October 31, 2003

Commissioner for Patents P. O. Box 1450 Alexandria VA 22313-1450

Sir:

This is an information disclosure statement submitted in compliance with the timing requirements of 37 C.F.R. §1.97(b)(1).

Attached are copies of one English-language and two Japanese-language articles. Any relevance of these articles can be gleaned from pages 1 and 2 of the present application, where these documents are discussed. The documents are listed on the attached Form PTO-1449.

Since this Information Disclosure Statement is being filed with the application, no certification or fee is required, and the requirements of 37 C.F.R. §§1.97 and 1.98 are deemed to be fully met as to the documents submitted. Consideration of the submitted documents is respectfully requested.

K. has

October 31, 2003

Date

Robert H. Berdo, Jr. (Reg. No. 38,075)

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Respectfully submitted

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FORM PTO-1449				Atty Docket	Application No.						
INFORMATION DISCLOSURE STATEMENT				OHG 139	To Be Assigned						
			Applicant								
			Shigeru YAMADA								
			Filing Date	Group Unit							
				October 31, 2	2003	To Be Assigned					
	U.S. PATENT DOCUMENTS										
Examiner Initial		Document Number	Date	1	Name	Class	Sub- Class	Filing Date			
	AA										
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		OTHER	(Including A	uthor, Title, Date,	Pertinent Pages, etc.)						
	AM	Nikkei Microdevices, February, 1999, p48-57									
	AN	N Nikkei Microdevices, February, 2000, p50-53									
,	AO	Amkor Technology etCSP TM , 2000, See Internet URL: http://www.amkor.com/Products/all_products/etcsp.cfm									
	AP										
Examiner					Date Considered						
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